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**Search scope:** US Granted US Applications JP (bibliographic data only)

**Years:** 1991-2008

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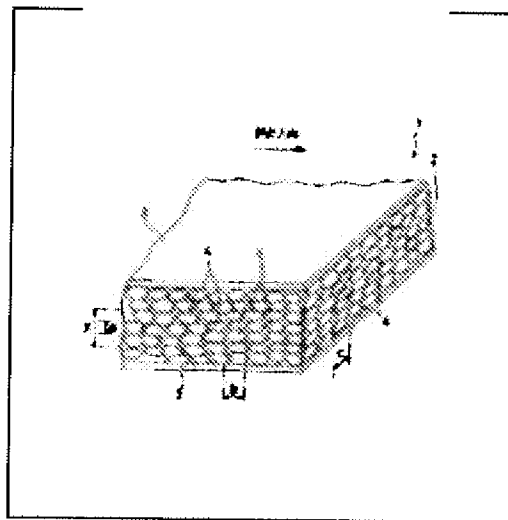
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**JP10000748 A**  
**POLYPROPYLENE-BASED RESIN FOAM**  
**LAMINATED SHEET AND MOLDING BODY**  
**THEREOF**  
**JSP CORP**

**Abstract:**

**PROBLEM TO BE SOLVED:** To improve characteristics such as lightweight properties, washability, toughness, rigidity or the like by a method wherein a foam laminated sheet, which has the specified flexural modulus and is suitable for a the stock such as a returnable container or the like, is produced by laminating a synthetic resin film having the specified tensile strength onto one side of a plate-like polypropylene-based resin foam having the specified density.



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**SOLUTION:** This foam laminated sheet 1 suitably used for a simple packaging box such as a returnable container or the like is produced by laminating synthetic resin film 3 onto both the sides of a plate-like polypropylene-based resin foam 2 as to have the flexural modulus of  $900-3,500 \text{ kg/cm}^2$ . In this plate-like polypropylene-based resin foam 2, the shape of each of bubbles existing within the portion, which exceeds 25% of the whole thickness from both the surfaces of the foam, satisfies the following formulae:  $0.40 \leq A/B \leq 1.0$ ,  $0.4 \leq A/C \leq 1.0$  and  $0.2 \leq (A+B+C)/3 \leq 1.5$ , in which A, B and C represent respectively average bubble diameter in thickness direction, extrusion direction and widthwise direction. The synthetic resin film 3, for which orientated polypropylene-based resin film is suitable, is used under the condition having the tensile strength of  $10 \text{ kg/mm}^2$  or more and the thickness of  $5-60 \mu\text{m}$ .

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B29C005114 B32B000518 B32B002700 B29K002300 B29L000900

**Current IPC-R:**

	invention	additional
<b>Advanced</b>	B32B000518 20060101	B29K002300 20060101
	B29C005114 20060101	B29L000900 20060101
	B32B002700 20060101	
	B32B002732 20060101	
	invention	additional
<b>Core</b>	B32B000518 20060101	
	B29C005114 20060101	
	B32B002700 20060101	
	B32B002732 20060101	

**Priority:**

JP1996175588A 19960614

**Patents Citing This One:**

- EP1174263 A1 20020123 SEKISUI CHEMICAL CO., LTD.
- JP3884670 B2 20070221
- US5091340 A 19920225 NEC Corporation
- US7063768 B2 20060620 Sekisui Chemical Co., Ltd.
- EP1174263 B1 20030618 SEKISUI CHEMICAL CO., LTD.
- US5420068 A 19950530 NEC Corporation
- US6986941 B2 20060117 JSP Corporation
- WO2008008875 A2 20080117 DOW GLOBAL TECHNOLOGIES INC

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